



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2814  
Examiner: Mr. Nathan W. Ha

In re PATENT APPLICATION of:

Applicant(s): Makoto TERUI et al.

Serial No.: 10/022,268

Filed: December 20, 2001

For: SEMICONDUCTOR PACKAGE AND  
METHOD OF FABRICATING SAME

Docket No: OKI 286

AMENDMENT

Commissioner of Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action of November 18, 2002, the period for reply to which is being extended to expire on March 18, 2003 by a petition filed concurrently herewith, kindly amend the above-identified application as follows:

IN THE TITLE/SPECIFICATION/ABSTRACT:

A substitute specification (including the title and abstract, but not the claims) is appended to this Amendment as Attachment A. Attachment A also includes a marked-up copy of the original specification to show the changes that have been included in the substitute specification.

Please enter the substitute specification.

IN THE CLAIMS:

Kindly cancel claims 1-8 without prejudice to a possible divisional application.  
Kindly also amend claims 9-15, and add new claims 16-21, so that a complete set of the pending claims will read as follows (it being noted that Attachment B is appended to this Amendment to show how the rewritten claims differ from the previous version of these claims):

9/a  
S. Mackey  
3-12-03

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